

Electroninks to Showcase Spray-Coated MOD Silver Ink for EMI Shielding at SEMICON Taiwan 2026

Company to exhibit at MANZ booth #M1248, spotlighting EI-1207 spray coating as a scalable, vacuum-free alternative to sputtering for EMI shielding



AUSTIN, TX, UNITED STATES, August 24, 2026 /EINPresswire.com/ -- [Electroninks](https://www.electroninks.com/), the leader in metal complex inks for additive manufacturing and advanced semiconductor packaging, today announced its participation in SEMICON Taiwan 2026, taking place September 2–4 at the Taipei Nangang Exhibition Center (TaiNEX 1 & 2). Electroninks will exhibit at booth #M1248, co-located with manufacturing partner MANZ, where the company will showcase its portfolio of MOD ([metal organic decomposition](#)) silver inks for spray coating and inkjet printing applications.

Representing Electroninks at the event will be a full roster of executives who will be on-site throughout the show to meet with customers, partners, and industry stakeholders exploring additive alternatives to traditional metallization.

ATTENDING EXECUTIVES:

- * Melbs LeMieux – President & Co-founder
- * Takashi Mochizuki – Director of Sales and Business Development
- * Brian Liu - APAC Sales Director
- * Johnson Ke - Director of Sales & Technical Services
- * Kazutaka Ozawa - Global Technical Director
- * Kang-Yu Liu- Taiwan Application Development Manager
- * Linus Wu - Engineer
- * Charlie Chiu - Engineer
- * Jet Cheng - Engineer
- * Johnny Hsieh - Operations Manager

At the booth, Electroninks will highlight [EI-1207](#), a particle-free, polymer-free silver MOD ink engineered for spray coating (and inkjet) applications in EMI shielding and advanced packaging.

The product offering enables non-line-of-sight deposition, cures in air atmosphere and delivers immediate metallization, good sidewall and corner coverage, and higher metal purity with low sheet resistance.

Because spray coating is not limited by line-of-sight physics, it enables uniform sidewall coverage up to 100 percent aspect ratio in package geometries with narrow spacing, compared to roughly 40 percent sidewall coverage for current state-of-the-art metalization. That coverage advantage allows manufacturers to skip the reconstitution step required in traditional workflows, reducing process steps while significantly increasing units per hour and packages per wafer ring.

Electroninks will present reliability and shielding effectiveness data for EI-1207 spray-coated films, which achieve greater than 30 dB of shielding across 1 MHz to 1 GHz at 2 microns of film thickness, and up to 60 dB at 1.2 microns or 80 dB at 3 microns across the 1 to 40 GHz range. The films maintain stable adhesion and electrical resistance through reliability testing and have passed customer qualification.

Electroninks' broader MOD ink platform spans the EI-12xx and EI-14xx series for spray coating and the EI-7xx and EI-11xx series for inkjet printing, giving manufacturers a range of process temperatures, resistivity, and adhesion profiles to match specific packaging and interconnect requirements.

"Our metalization products for EMI shielding have been in qualification and reliability testing for the past couple of years. Now qualified from a reliability and performance standpoint, customers are looking to adopt for not only cost and UPH benefits, but also the functional advantages," said Melbs LeMieux, co-founder and president of Electroninks. "Spray-coated MOD silver gives manufacturers sidewall coverage sputtering simply cannot reach, with significant ESG benefits. At SEMICON Taiwan, we're looking forward to showing the industry what that means in practice, not just in the data."

Attendees are invited to visit Electroninks at booth #M1248 to see live demonstrations of the spray coating process and to discuss how MOD ink technology can be integrated into existing manufacturing lines.

For more information on Electroninks products and solutions, please visit www.electroninks.com.

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About Electroninks

Electroninks Incorporated is a world-leader in the commercialization of advanced materials for

electronics and semiconductor packaging. We have developed a full suite of proprietary metal complex conductive ink solutions and complementary material sets, thus accelerating time to market for both new innovations and drop-in manufacturing breakthroughs.

Electroninks' metal complex inks – including silver, gold, platinum, nickel and copper – deliver higher conductivity, manufacturing flexibility, and cost-effectiveness. The company's conductive inks provide reliable solutions for applications in printed circuit board (PCB) manufacturing, semiconductor packaging, consumer electronics, wearables, medical devices and more. We also partner closely with best-in-class equipment and integration partners to provide customers with a total ink and process solution with the ultimate goal of reducing manufacturing costs and complexity.

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